

07-16-2002



Form PTO-1595 (Rev. 03/01)

U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/2002)

102157704

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): 7.18.02 Massachusetts Institute of Technology

2. Name and address of receiving party(ies) Name: National Science Foundation Internal Address: Office of the General Counsel Suite 1265 Street Address: 4201 Wilson Boulevard City: Arlington State: VA Zip: 22239

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance: Assignment Merger Security Agreement Change of Name Other Confirmatory License

Execution Date: 03/20/02

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) 08/551,012 B. Patent No.(s) Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Robin Clay Fritsch Internal Address: Office of the General Counsel Suite 1265 Street Address: 4201 Wilson Boulevard City: Arlington State: VA Zip: 22230

6. Total number of applications and patents involved: 7. Total fee (37 CFR 3.41) \$ 0.00 Enclosed Authorized to be charged to deposit account

8. Deposit account number:

DO NOT USE THIS SPACE

9. Signature. Robin Clay Fritsch Name of Person Signing Signature Date 7/2/02

Total number of pages including cover sheet, attachments, and documents:

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

PATENT REEL: 013078 FRAME: 0726

LICENSE TO THE UNITED STATES GOVERNMENT

WHEREAS, Emanuel Sachs, et al. has invented "Enhancement of Thermal Properties of Tooling Made By Solid Free Form Fabrication Technique" and filed a patent application thereon in the United States, entitled "Enhancement of Thermal Properties of Tooling Made By Solid Free Form Fabrication Techniques" and bearing Serial Number 08/551,012 and filing date October 31, 1995; and

WHEREAS, invention was made in the course of research supported by the National Science Foundation under N.S.F. Grants DDM-8913977 and 9215728-DDM; and

WHEREAS, the United States Government is entitled to certain rights in and to said invention and application by reason of the terms relating to such support; and

WHEREAS, the Massachusetts Institute of Technology, hereinafter called the "Licensor" has acquired by assignment from the inventors the entire right, title and interest of the inventors to such invention;

NOW, THEREFORE:

1. The Licensor, in consideration of the premised and other good and valuable consideration, hereby grants and conveys to the United States Government a non-exclusive, non-transferable, paid-up license to make, use and sell the invention throughout the world by or on behalf of the Government of the United States and states and domestic municipal governments under the aforesaid patent application and any and all divisions or continuations, and in any and all patents or reissues which may be granted thereon during the full term or terms thereof.

2. The Licensor covenants and warrants that he has the right to grant the foregoing license, and that any assignment or license which he may make of the invention or the said patent application or patents thereon, shall expressly be make subject to this license.

3. The Licensor agrees that the Government shall not be estopped at any time to contest the enforceability, validity, scope of or title to any patent or patent application herein licensed.

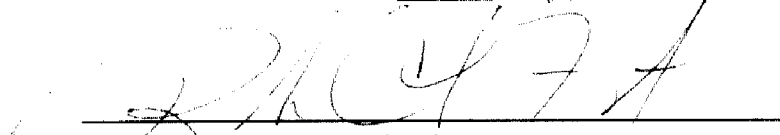
4. This License shall not limit the rights reserved to the Government under the contract(s), grant(s), or other arrangement(s) under which said invention was made.

Signed this 3 day of April, 1998 .

MASSACHUSETTS INSTITUTE OF TECHNOLOGY

  
\_\_\_\_\_  
Jarmila Z. Hrbek  
Patent Administrator/Office Manager

Accepted for the benefit of the Government this 20 May 02

  
\_\_\_\_\_  
Patent Paralegal  
NATIONAL SCIENCE FOUNDATION